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FLIP CHIP ON GLASS IMAGE SENSOR PACKAGE

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ABSTRACT

10 An image sensor package includes an image sensor  
having an active area and bond pads on a front surface  
of the image sensor. A window is mounted to the image  
sensor by flip chip bumps formed between the bond pads  
of the image sensor and interior traces on an interior  
surface of the window. The window has an area less  
than an area of the front surface of the image sensor.  
A bead is formed between the window and the front  
15 surface of the image sensor thus forming a sealed  
cavity in which the active area is located. The bead  
has sides coplanar with sides of the image sensor such  
that the image sensor package is chip size.